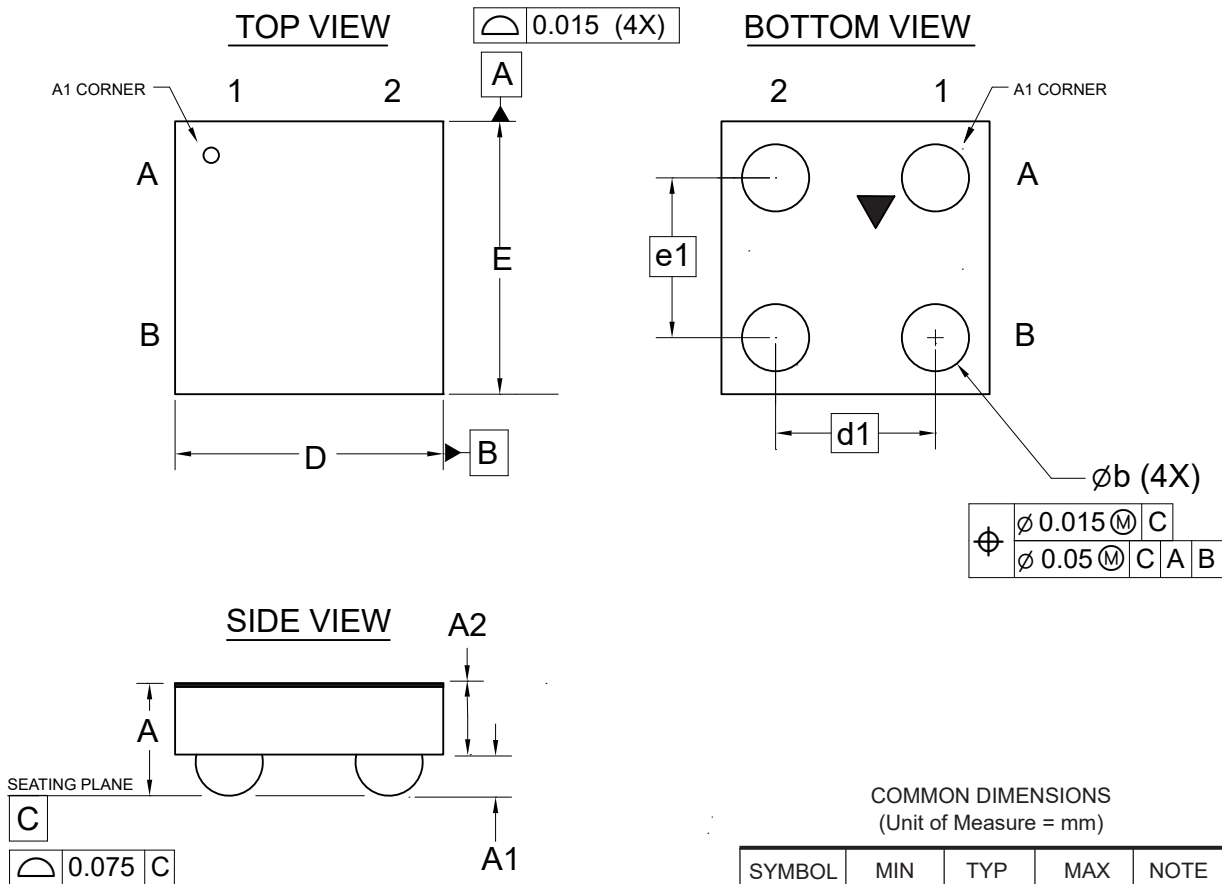




PIN ASSIGNMENT MATRIX

	1	2
A	V _{CC}	GND
B	SCL	SDA

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	—	0.070	—	
A2	—	0.225	—	3
D	Contact Microchip for Details			
d1	0.400 BSC			
E	Contact Microchip for Details			
e1	0.400 BSC			
b	—	0.162	—	

Note: 1. Dimensions are NOT to scale.
2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
3. Product offered with Back Side Coating (BSC)

10/1/15

TITLE
4U-13, 4-ball 2x2 Array, 0.40mm Pitch
Wafer Level Chip Scale Package (WLCSP) with BSC

GPC
GUJ

DRAWING NO.
4U-13

REV.
A